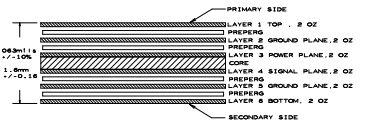
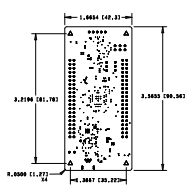
| REVISIONS | | | |
|---|---|---|---|
| REV | DESCRIPTION | DATE | APPROVED |
| 1 | INITIAL RELEASE | 04/11/15 | RAJA |
| 2 | ALPHA RELEASE | 01/12/15 | RAJA |
| 3 | BETA RELEASE | 22/12/15 | RAJA |
| 4 | PRODUCTION RELEASE | 01/04/16 | RAJA |




## NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPLIANT SYMBOL IN
      SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER, PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR =BLUE=
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL & IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WARP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.
12. VIA FILLING REQUIRED FOR ALL VIAS.
13. CARE MUST BE TAKEN TO AVOID OVER ETCHING OF COPPER ON PADS.




| DRILL CHART: TOP to BOTTOM | | | | |
|---|---|---|---|---|
| ALL UNITS ARE IN MILLIMETERS | | | | |
| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
| - | 0.3658 | +0.0762/-0.0762 | PLATED | 135 |
| - | 0.254 | +0.0/-0.254 | PLATED | 16 |
| - | 0.254 | +0.0762/-0.0762 | PLATED | 110 |
| - | 0.381 | +0.0762/-0.0762 | PLATED | 10 |
| + | 0.1118 | +0.0762/-0.0762 | PLATED | 5 |
| + | 1.000 | +0.0762/-0.0762 | PLATED | 100 |
| △ | 0.178 | +0.0000/-0.000[illegible] | PLATED | 4 |
| ⊡ | 1.0000+0.781 | +0.0762/-0.0762 | PLATED | 2 |

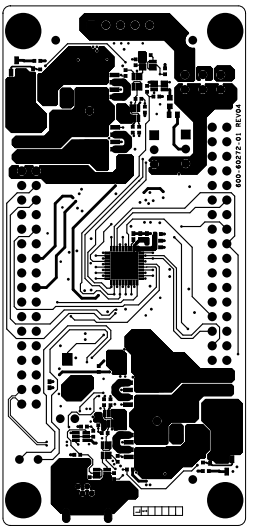
| UNLESS OTHERWISE SPECIFIED | SIGNATURES | | DATE |
|---|---|---|---|
| DIMENSIONS ARE IN INCHES | DRAWN : HUSAIN | | 01/04/16 |
| TOLERANCES ON: ANGLES +/- 2° | CHECKED : RAJA | | 01/04/16 |
| 2 PL DECIMALS +/- .010 | ENGNG : RAGO | | 01/04/16 |
| 3 PL DECIMALS +/- .000 | ISSUED | | |
| TAPER ANGLE | | | |
| PROJECTIONS | | | |

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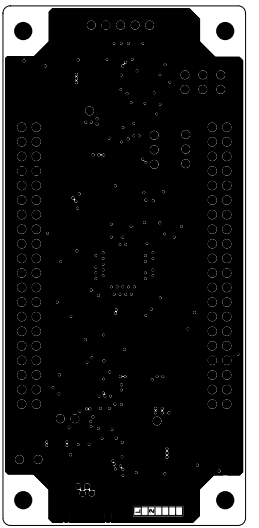
CYPRESS SEMICONDUCTOR
198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

# FABRICATION DRAWING
# CY4541 CCG4 DAUGHTER CARD

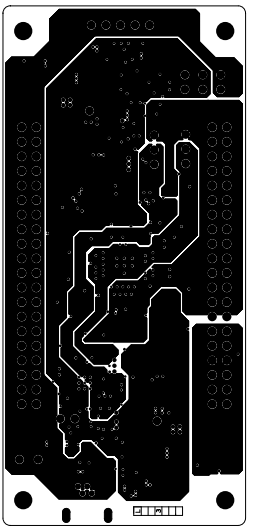
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| C | | 610-60276-01 | 04 |
| SCALE: 1/1 | | SHEET: 1 OF 1 | |



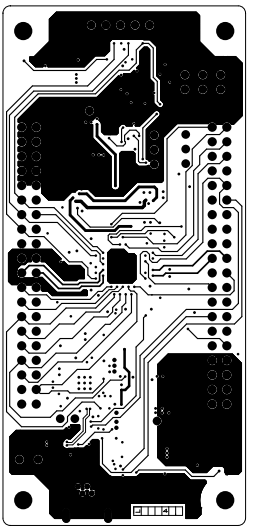

600-60272-01 REV04 PRIMARY SIDE



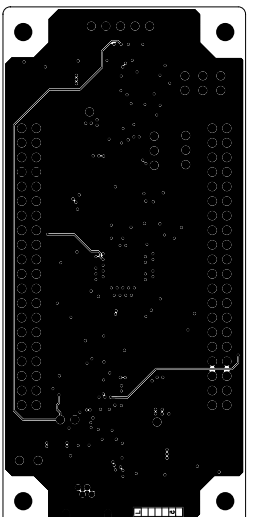
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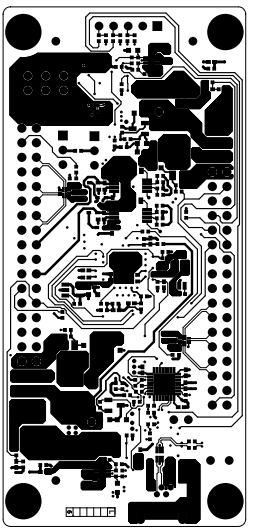
600-60272-01 REV04 POWER1 LAYER



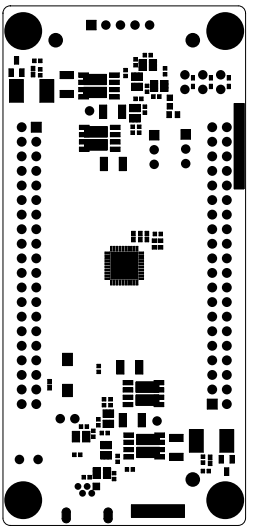
600-60272-01 REV04 SIGNAL1 LAYER



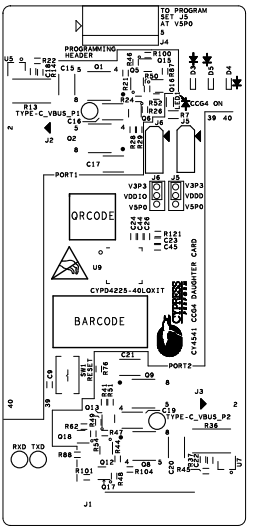
600-60272-01 REV04 GROUND2 LAYER



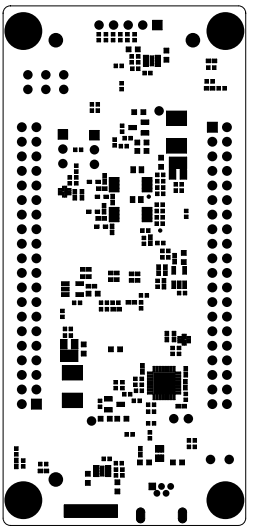
600-60272-01 REV04 SECONDARY SIDE



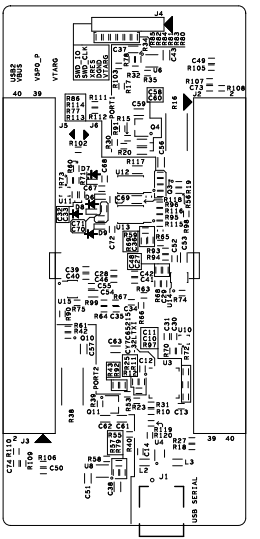
600-60272-01 REV04 PRIMARY SOLDERMASK




600-60272-01 REV04 PRIMARY SILKSCREEN



600-60272-01 REV04 SECONDARY SOLDER MASK



600-60272-01 REV04 SECONDARY SILKSCREEN